

Datasheet revision 1.0 <u>www.chipquik.com</u>

Solder Wire Sn63/Pb37 No-Clean with 2.2% Flux Core 1lb Spool

Product Highlights

No-Clean Synthetic Flux Core

The clear, non-corrosive, non-conductive residue is meant to be left on the board.

2.2% flux core

Halogen content: None



Alloy: Sn63/Pb37
Wire Diameter: 0.015" (0.38mm)
Flux Type: No-Clean Synthetic

Flux Classification: ROL0

Melting Point: 183°C (361°F)
Packaging: 1 lb Spool
Shelf Life: >60 months



Test Results

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Test J-STD-004 or other	Test Requirement	Result
requirements as stated		
Copper Mirror	IPC-TM-650: 2.3.32	L: No breakthrough
Corrosion	IPC-TM-650: 2.6.15	L: No corrosion
Quantitative Halides	IPC-TM-650: 2.3.28.1	L: <0.05%
Electrochemical Migration	IPC-TM-650: 2.6.14.1	L: <1 decade drop (No-clean)
Surface Insulation Resistance 85°C,	IPC-TM-650: 2.6.3.7	L: ≥100MΩ (No-clean)
85% RH @ 168 Hours		,
Visual	IPC-TM-650: 3.4.2.5	Clear and free from precipitation
Conflict Minerals Compliance	Electronic Industry Citizenship Coalition (EICC)	Compliant
REACH Compliance	Articles 33 and 67 of Regulation (EC) No 1907/2006	Contains Lead (Pb) CAS# 7439-92-1 No other SVHC present

Conforms to the following Industry Standards:

J-STD-004B, Amendment 1 (Solder Fluxes):

J-STD-006C, Amendments 1 & 2 (Solder Alloys and Fluxed/Non-Fluxed Solders):

RoHS 3 Directive (EU) 2015/863:

Yes

No